

Product Description

Shin-Etsu's PCS-PL-30 is a thermally conductive phase-change material designed to conform to the substrates that it is applied to. PCS-PL-30 exhibits excellent thermal conductivity and adhesion to metal and graphite substrates.

Product Features

- Conforms to substrate after application of heat
- Excellent thermal conductivity
- Thermal resistance minimization due to conformation to substrates
- High tackiness
- Excellent pump-out resistance

Typical Applications

- Vehicle inverters/converters
- Power modules
- LED modules

Typical Properties

Type	Phase Change Material
Color	White
Density @ 23C (g/cm ³)	2.70
Dielectric Strength (kV/mm)	6.0
Thermal Conductivity (W/m·K)	1.70
Thermal Resistance (mm ² ·K/W)	73
Softening Point	50
Thickness (mm)	0.120
Reinforced Layer	Polyimide
Bond Line Thickness (µm)	30
Sheet Size (mm)	320 x 400

Note: Values are not for specification purposes.

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